

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) ~~A MEMS array characterized by being provided with~~ An array comprising:

pluralities of various types of elements for each type, and
switches for connecting said elements, wherein
some of said elements are interconnected by determining an on/off state of
all of said switches so as to make a circuit, and
some of said elements are produced on a substrate by utilizing Micro
Electro-Mechanical System technology, and by enabling the elements to be freely
interconnected.

2. (Currently Amended) ~~A MEMS~~ An array as set forth in claim 1,
wherein the switches connecting the elements are semiconductor switches.

3. (Withdrawn) A MEMS array as set forth in claim 1, wherein the
switches connecting the elements are mechanical switches.

4. (Currently Amended) ~~A MEMS~~ An array as set forth in claim 1,
provided with ~~a substrate and~~ an interconnect layer, said substrate being formed

with said switches, said interconnect layer provided with a plurality of elements connected through said switches.

5. (Currently Amended) ~~A-MEMS~~ An array as set forth in claim 4, wherein said substrate is provided with drive parts for driving said switches.

6. (Currently Amended) ~~A-MEMS~~ An array as set forth in claim 5, wherein said substrate is further provided with semiconductor circuits for signal processing.

7. (Currently Amended) ~~A-MEMS~~ An array as set forth in claim 6, wherein said semiconductor circuits have three-dimensional structures.

8. (Currently Amended) ~~A-MEMS~~ An array as set forth in claim 1, provided with ~~a substrate and~~ an interconnect layer, said interconnect layer provided with a plurality of elements and switches for connecting the elements.

9. (Currently Amended) ~~A-MEMS~~ An array as set forth in claim 8, wherein said substrate is provided with drive parts for driving said switches.

10. (Currently Amended) ~~A-MEMS~~ An array as set forth in claim 9, wherein said substrate is provided with semiconductor circuits for signal processing.

11. (Currently Amended) ~~A MEMS~~ An array as set forth in claim 10, wherein said semiconductor circuits have three-dimensional structures.

12. (Withdrawn) A MEMS array as set forth in claim 1, provided with a substrate and interconnect layer, said interconnect layer provided with a plurality of elements, switches for connecting said elements being provided on the interconnect layer.

13. (Withdrawn) A MEMS array as set forth in claim 12, wherein said substrate is provided with drive parts for driving said switches.

14. (Withdrawn) A MEMS array as set forth in claim 13, wherein said substrate is provided with semiconductor circuits for signal processing.

15. (Withdrawn) A MEMS array as set forth in claim 14, wherein said semiconductor circuits have three-dimensional structures.

16. (Currently Amended) ~~A MEMS~~ An array as set forth in claim 1, wherein the same package packages semiconductor circuits built ~~[[in]]~~ therein.

17. (Withdrawn) A method of production of a MEMS array providing an interconnect layer on a substrate, said method of production of a MEMS array

characterized by having: a step of forming a plurality of switches in said substrate and a step of forming pluralities of various types of elements for each type connected through said plurality of switches in said interconnect layer.

18. (Withdrawn) A method of production of a MEMS array providing an interconnect layer on a substrate, said method of production of a MEMS array characterized by having: a step of forming pluralities of various types of elements for each type in said interconnect layer and a step of providing a plurality of switches for connecting said elements on said interconnect layer.

19. (Withdrawn) A method of production of a MEMS array providing an interconnect layer on a substrate, said method of production of a MEMS array characterized by having: a step of forming switch drive parts on said substrate, a step of forming pluralities of various types of elements for each type in said interconnect layer, and a step of providing a plurality of switches for connecting said elements on said interconnect layer.

20. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array and a step of forming an

interconnect layer connecting elements in accordance with the connection states of said switches.

21. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array, a step of forming an interconnect layer connecting elements in accordance with the connection states of said switches on the substrate of said MEMS device, and a step of forming a plurality of elements of the same arrangement as the MEMS array on said interconnect layer.

22. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array, a step of providing switches in the substrate of the MEMS device, a step of providing an additional interconnect layer for short-circuiting, opening, or connecting said switches in accordance with the connection states of said switches on the substrate of the MEMS device, and a step of providing an interconnect layer arranging a plurality of elements of

the same arrangement as said MEMS array on said additional interconnect layer.

23. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array, a step of forming an interconnect layer providing a plurality of elements of the same arrangement as said MEMS array, and a step of selectively forming switches and interconnects on said interconnect layer based on the connection states of said switches.